

What is claimed is:

1. A semiconductor device, comprising:  
fuse terminals provided on a chip substrate surface;  
and

5 a discharge contribution terminal which is provided  
at the upper side on said chip substrate surface and of which  
the height from said chip substrate surface to the top face is  
higher than the height of the top face of said fuse terminals.

2. The semiconductor device according to Claim 1,  
10 wherein said discharge contribution terminal is a chip terminal.

3. The semiconductor device according to Claim 1,  
wherein said discharge contribution terminal is a dummy  
terminal which is disposed so as to surround the fuse terminals.

4. The semiconductor device according to Claim 3,  
15 wherein said dummy terminal is electrically connected to a  
reference voltage power supply.